

OK TO ENTER: /MR/



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

**Toshihiro TSUCHIYA**

Application No.: 10/523,976

Filed: February 8, 2005

For: WAFER POLISHING METHOD AND APPARATUS

Attorney Docket No.: ISH-0227

Examiner: M. T. Rachuba

Art Unit: 3723

Confirmation No.: 1124

**AMENDMENT AFTER FINAL REJECTION UNDER 37 C.F.R. §1.116**

**Mail Stop AF**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

**I. INTRODUCTORY COMMENTS**

In response to the final Office Action dated April 12, 2007, please amend the above-identified application as set forth below.

Claims 2 and 3 are pending in the application. By this Amendment, claims 1, 4 and 5 are canceled without prejudice or disclaimer.

Applicants express their appreciation for the Examiner's allowance of claims 2 and 3. It is respectfully submitted that the application is now in condition for allowance.

**II. AMENDMENTS TO THE DRAWINGS**

(There are no amendments to the drawings)

**III. AMENDMENTS TO THE SPECIFICATION**

(There are no amendments to the specification)